

## Thermal Characteristics

Package	$I_D$ (continuous) <sup>†</sup> (mA)	$I_D$ (pulsed) (A)	Power Dissipation @ $T_c = 25^\circ\text{C}$ (W)	$\theta_{jc}$ ( $^\circ\text{C/W}$ )	$\theta_{ja}$ ( $^\circ\text{C/W}$ )	$I_{DR}^{\dagger}$ (mA)	$I_{DRM}$ (A)
TO-92	450	2.40	1.0	125	170	450	2.40
TO-243AA (SOT-89)	630	2.90	1.6 <sup>‡</sup>	15	78 <sup>‡</sup>	630	2.90

### Notes:

<sup>†</sup>  $I_D$  (continuous) is limited by max rated  $T_J$ .

<sup>‡</sup>  $T_A = 25^\circ\text{C}$ . Mounted on FR5 Board, 25mm x 25mm x 1.57mm. Significant  $P_D$  increase possible on ceramic substrate.

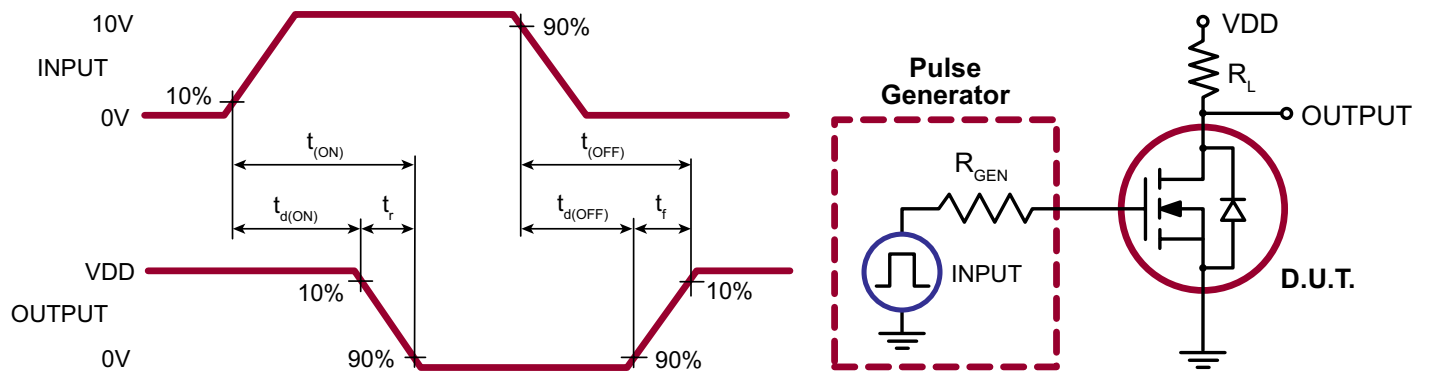
## Electrical Characteristics ( $T_A = 25^\circ\text{C}$ unless otherwise specified)

Sym	Parameter		Min	Typ	Max	Units	Conditions
$BV_{DSS}$	Drain-to-source breakdown voltage		40	-	-	V	$V_{GS} = 0V, I_D = 1.0mA$
$V_{GS(th)}$	Gate threshold voltage		0.6	-	1.6	V	$V_{GS} = V_{DS}, I_D = 500\mu A$
$\Delta V_{GS(th)}$	Change in $V_{GS(th)}$ with temperature		-	-3.8	-5.0	mV/ $^\circ\text{C}$	$V_{GS} = V_{DS}, I_D = 1.0mA$
$I_{GSS}$	Gate body leakage		-	0.1	100	nA	$V_{GS} = \pm 20V, V_{DS} = 0V$
$I_{DSS}$	Zero gate voltage drain current		-	-	1.0	$\mu A$	$V_{GS} = 0V, V_{DS} = \text{Max Rating}$
			-	-	100		$V_{DS} = 0.8 \text{ Max Rating}, V_{GS} = 0V, T_A = 125^\circ\text{C}$
$I_{D(ON)}$	On-state drain current		-	0.35	-	A	$V_{GS} = 3.0V, V_{DS} = 20V$
			0.5	1.1	-		$V_{GS} = 5.0V, V_{DS} = 20V$
			2.0	2.6	-		$V_{GS} = 10V, V_{DS} = 20V$
$R_{DS(ON)}$	Static drain-to-source on-state resistance	Both packages	-	5.0	-	$\Omega$	$V_{GS} = 3.0V, I_D = 50mA$
			-	2.3	2.5		$V_{GS} = 5.0V, I_D = 250mA$
		TO-92	-	1.5	1.8		$V_{GS} = 10V, I_D = 1.0A$
		TO-243AA	-	-	2.0		
$\Delta R_{DS(ON)}$	Change in $R_{DS(ON)}$ with temperature		-	0.7	1.0	%/ $^\circ\text{C}$	$V_{GS} = 10V, I_D = 1.0A$
$G_{FS}$	Forward transductance		340	450	-	mmho	$V_{DS} = 20V, I_D = 500mA$
$C_{ISS}$	Input capacitance		-	-	70	pF	$V_{GS} = 0V, V_{DS} = 20V, f = 1.0MHz$
$C_{OSS}$	Common source output capacitance		-	-	50		
$C_{RSS}$	Reverse transfer capacitance		-	-	15		
$t_{d(ON)}$	Turn-on delay time		-	3.0	5.0	ns	$V_{DD} = 20V, I_D = 1.0A, R_{GEN} = 25\Omega$
$t_r$	Rise time		-	7.0	8.0		
$t_{d(OFF)}$	Turn-off delay time		-	6.0	9.0		
$t_f$	Fall time		-	5.0	8.0		
$V_{SD}$	Diode forward voltage drop	TO-92	-	1.2	1.8	V	$V_{GS} = 0V, I_{SD} = 1.0A$
		TO-243AA	-	-	2.0		$V_{GS} = 0V, I_{SD} = 0.5A$
$t_{rr}$	Reverse recovery time		-	300	-	ns	$V_{GS} = 0V, I_{SD} = 1.0A$

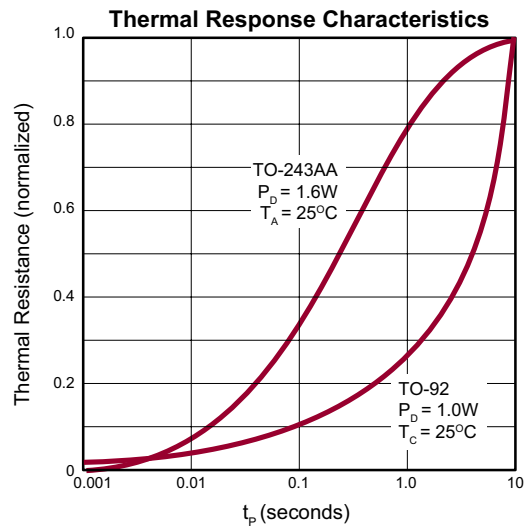
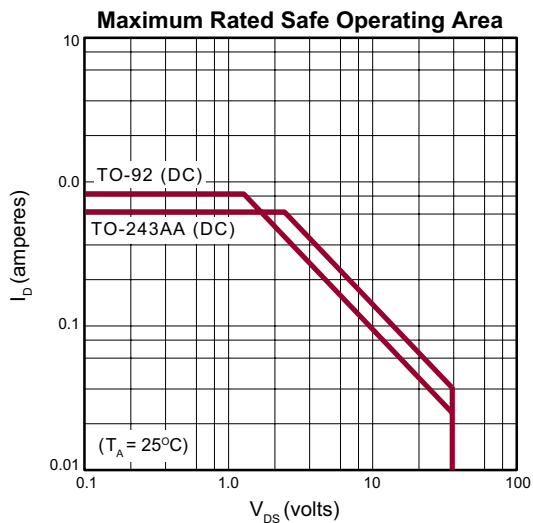
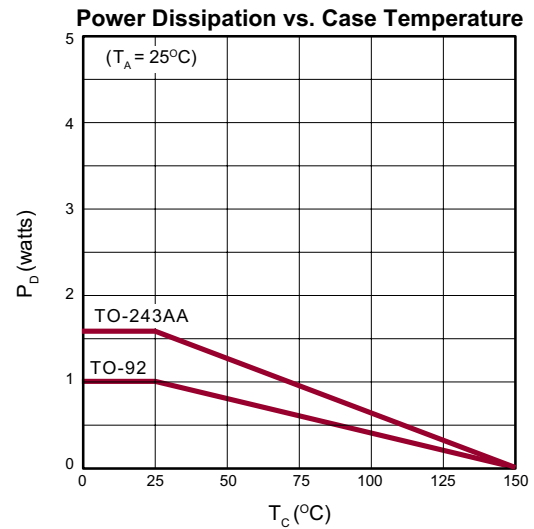
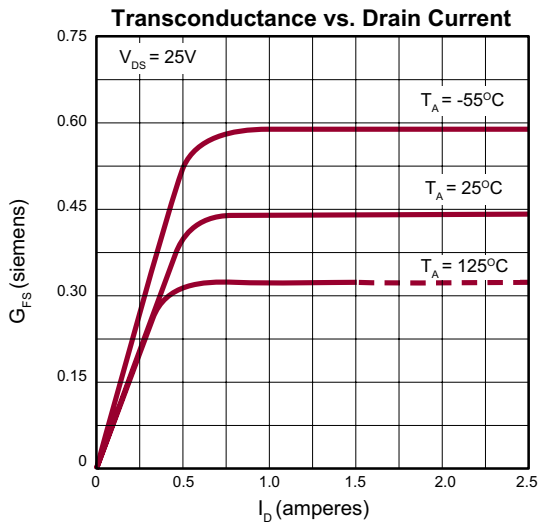
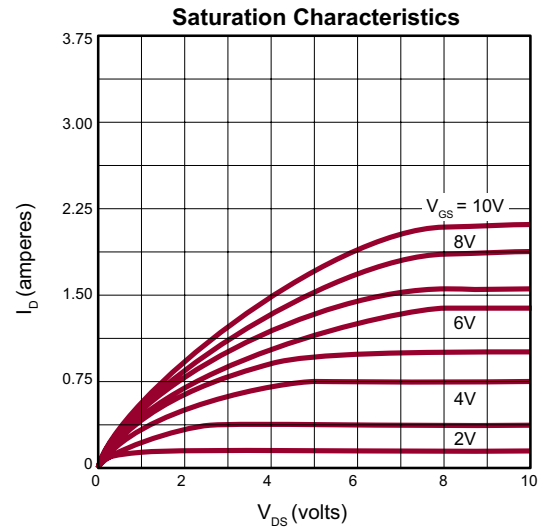
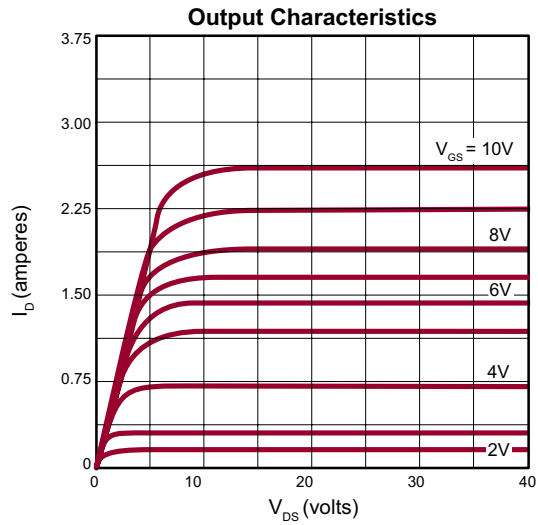
### Notes:

1. All D.C. parameters 100% tested at  $25^\circ\text{C}$  unless otherwise stated. (Pulse test: 300 $\mu s$  pulse, 2% duty cycle.)
2. All A.C. parameters sample tested.

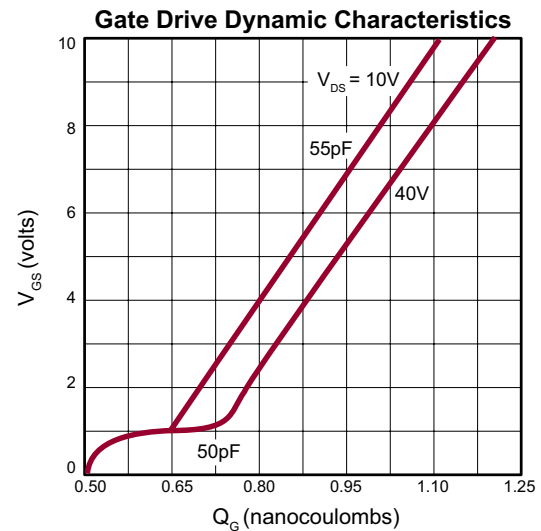
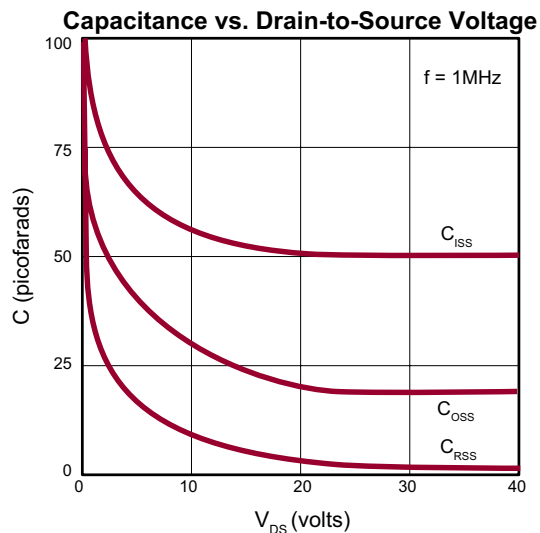
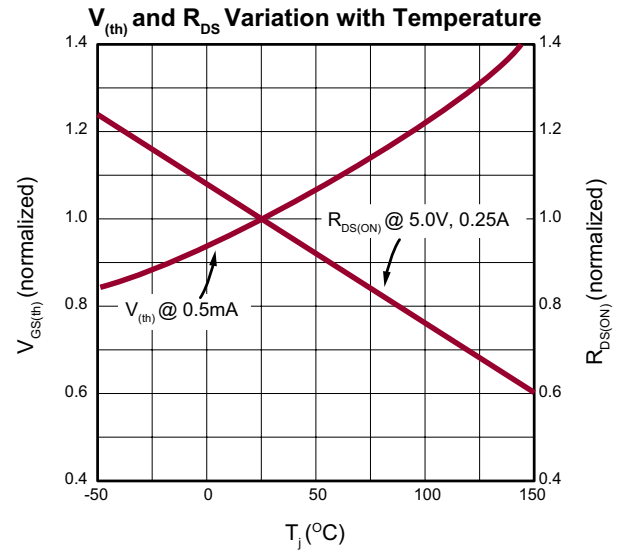
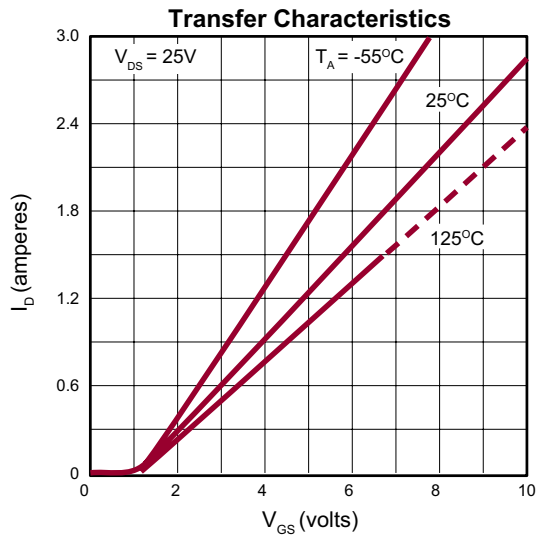
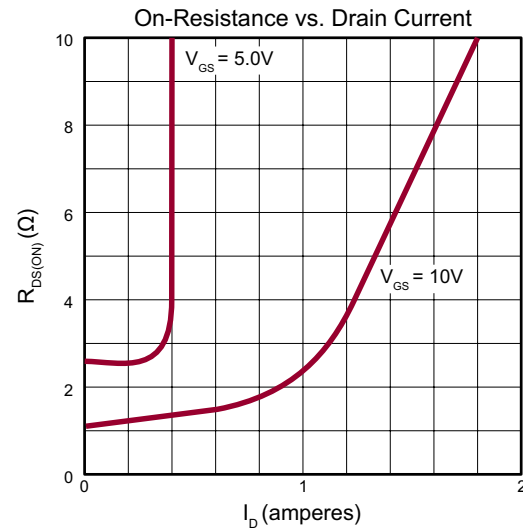
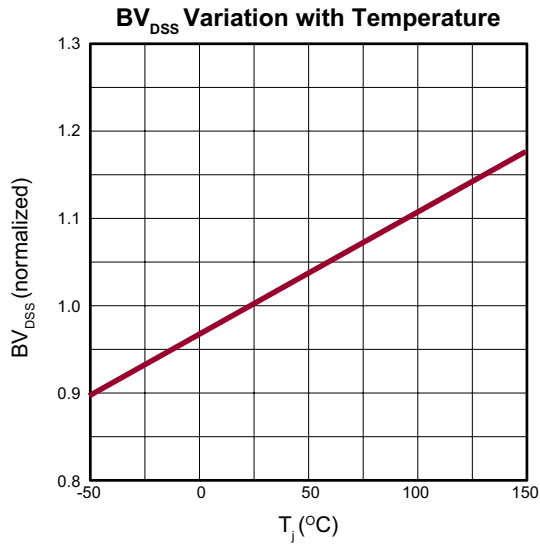
## Switching Waveforms and Test Circuit



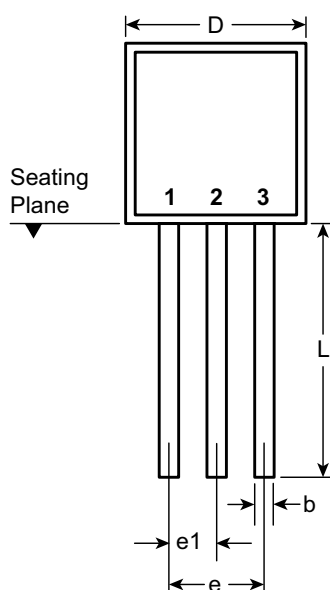
## Typical Performance Curves



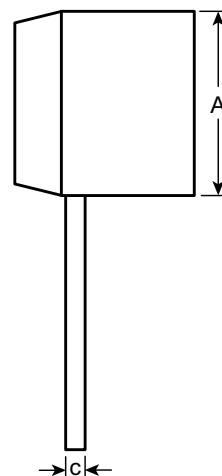
## Typical Performance Curves (cont.)



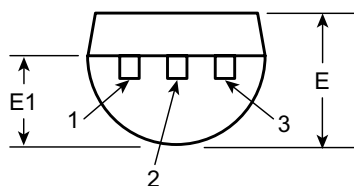
### 3-Lead TO-92 Package Outline (N3)



**Front View**



**Side View**



**Bottom View**

Symbol		A	b	c	D	E	E1	e	e1	L
Dimensions (inches)	MIN	.170	.014 <sup>†</sup>	.014 <sup>†</sup>	.175	.125	.080	.095	.045	.500
	NOM	-	-	-	-	-	-	-	-	-
	MAX	.210	.022 <sup>†</sup>	.022 <sup>†</sup>	.205	.165	.105	.105	.055	.610*

JEDEC Registration TO-92.

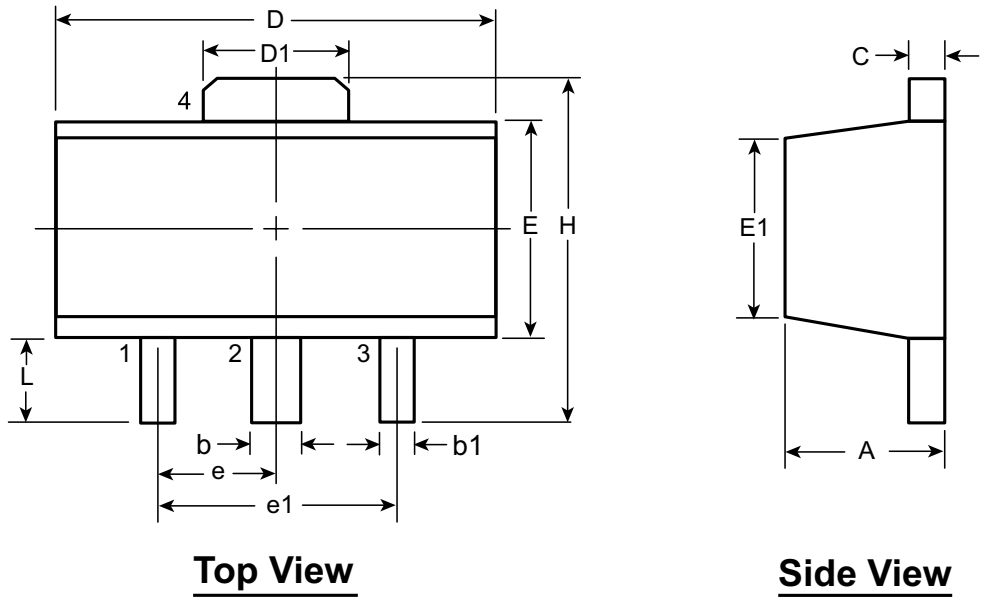
\* This dimension is not specified in the JEDEC drawing.

† This dimension differs from the JEDEC drawing.

**Drawings not to scale.**

**Supertex Doc.#:** DSPD-3TO92N3, Version E041009.

3-Lead TO-243AA (SOT-89) Package Outline (N8)



Symbol		A	b	b1	C	D	D1	E	E1	e	e1	H	L
Dimensions (mm)	MIN	1.40	0.44	0.36	0.35	4.40	1.62	2.29	2.00†	1.50 BSC	3.00 BSC	3.94	0.73†
	NOM	-	-	-	-	-	-	-	-			-	-
	MAX	1.60	0.56	0.48	0.44	4.60	1.83	2.60	2.29			4.25	1.20

JEDEC Registration TO-243, Variation AA, Issue C, July 1986.

† This dimension differs from the JEDEC drawing

Drawings not to scale.

Supertex Doc. #: DSPD-3TO243AAN8, Version F111010.

(The package drawing(s) in this data sheet may not reflect the most current specifications. For the latest package outline information go to <http://www.supertex.com/packaging.html>.)

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